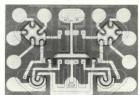
# LOAD-COMPENSATED DTL INTEGRATED CIRCUIT

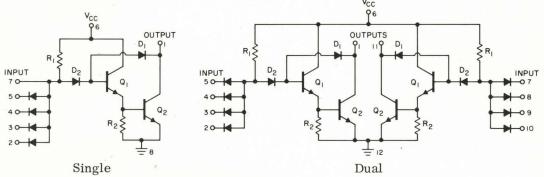
## TYPES ZAO1A AND ZAO2A SINGLE AND DUAL NAND/NOR GATES

## ONE OR TWO DIODE-TRANSISTOR LOGIC CIRCUITS IN A SINGLE CHIP OF SILICON

- Low Power-Speed Product 60 pico-watt-sec
- Operates From Single Power Supply
- Typical Propagation Delay Time 12 nsec
- Typical Power Dissipation 5mw
- High Fan-Out-5 at -55 to 70°C



#### CIRCUIT DIAGRAMS

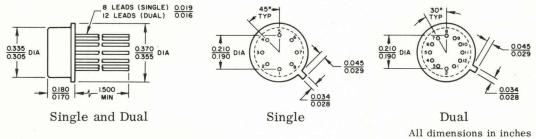


The logic operation of this circuit is identical with conventional DTL. The unique emitter-follower diode-clamp arrangement provides high-speed switching, high gain and low-power operation.

## MECHANICAL DATA

Single gate in modified 8-lead TO-5 package Dual gate in modified 12-lead TO-5 package (both available in flat package by July 1963)

Pin 8 (single) and pin 12 (dual) are in electrical contact with the case.



## PRODUCT CONDITIONING

Long life and mechanical reliability are ensured by subjecting <u>each unit</u> to the following tests:

- High Temperature Storage: 72 hours at 200°C
- Thermal Shock: +200°C to -65°C for 5 Cycles
- 30,000G Centrifuge in the Y<sub>1</sub> Plane
- Helium and Gross Leak Tests for Hermeticity
- Post-Bake Clean-Up to Assure Solderability



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## OPERATIONAL CHARACTERISTICS AT VCC=4v

Characteristic	Min	Тур	Max	Unit
Fan-in at -55 to +70°C			4 <sup>†</sup>	
Fan-out at $T_A = 70^{\circ}C$ , $\Delta V = 0.1 \text{ v (see Note 1)}$			5	
Worst-Case DC Stability, ΔV, at 70°C Fan-out = 5	100			mv
Power Dissipation per Gate at 25°C (see Note 2)		5		mw
Average Propagation Delay per Gate (see pp. 3,4), When Fan-in = 1 and Fan-out = 1, at $T_A = +25^{\circ}C$ $T_A = -55^{\circ}C$ $T_A = 70^{\circ}C$		12 14 14	15	nsec nsec nsec

<sup>†</sup> Diode array available for single gate to improve fan-in.

## ABSOLUTE MAXIMUM RATINGS AT 25° C

Power Supply Voltage, V <sub>CC</sub>										6 v
Gate Input Voltage										6 v
Gate Output Voltage (Input Grounded)										
Operating Temperature Range									-55	to +70°C
Storage Temperature Range	-								-55	to +200°C

## STATIC CHARACTERISTICS (WORST-CASE) VCC=4v

(See opposite page for test conditions)

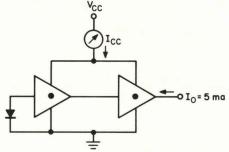
	Characteristic	Т	Unit			
	Characteristic	-55°C	+25°C	+70°C	Onic	
I <sub>OFF</sub>	Maximum Output Current with Gate OFF	5*	10*	20*	μа	
I <sub>R(max)</sub>	Maximum Reverse Current per Input Diode	0.05*	0.10*	0.30*	μа	
I i(max)	Maximum Input Current with Gate OFF (Max Load Presented to Driving Stage), with $V_i = V_F$ -100 mv	1.15*	1.30*	1.35*	ma	
V <sub>F</sub>	Maximum Voltage at any Input that will Ensure Turn-OFF (Max False Voltage)	1.38*	1.14*	0.95*	v	
V <sub>o(max)</sub>	Maximum Output Voltage When Fully Loaded at: Fan-out = 5 Fan-out = 25	1.02 1.30*	0.94*	0.85*	v v	
$V_T$	Minimum Input Voltage that will Ensure Turn-ON (Minimum True Voltage) Fan-out = 5	2.00	1.78	1.62	v	
ΔV	DC Stability Margin (V <sub>F</sub> - V <sub>o</sub> ) Fan-out = 5	0.36*	0.20*	0.10*	v	

<sup>\*</sup>Characteristics so designated are tested on every unit

#### Notes:

- 1. This is the maximum fan-out permissible for worst-case logic design with a 4 v power supply when the d-c stability  $\Delta V$  margin is 0.1 v.
- Power dissipation is defined as power supply voltage times average current drawn per gate. (See test circuit, p. 3).

## MEASUREMENT OF STATIC CHARACTERISTICS



Power Dissipation Test Circuit

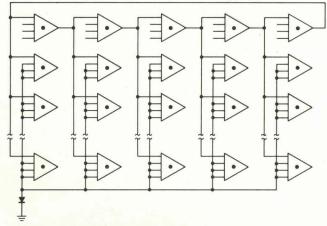
Power dissipation per gate =  $\frac{V_{CC} \times I_{CC}}{2}$ As measured above, the power dissipation is the average between the OFF stage and typically loaded ON stage and is equivalent to a 50% duty cycle for a single gate.

#### TEST CONDITIONS

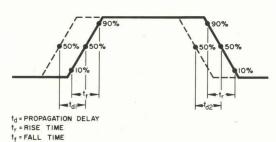
Characteristic to be	Set or Measure e.g., to Detern V <sub>o</sub> at 4 v, Mea	Other			
Determined	I <sub>i</sub> Input Current	V <sub>i</sub> Input Voltage	I。 Output Current	V <sub>o</sub> Output Voltage	Conditions
$ m V_{F}$		Measure	I *	4 v	Free inputs connected to $V_{CC}$
I <sub>i(max)</sub>	Measure	V <sub>F</sub> * -100 mv	×	4 v	Free inputs connected to V <sub>CC</sub>
I <sub>R(max)</sub>	Measure	4 v			Open circuit output One input grounded
Vo(max)	F.I. $\left[I_{OFF}^* + {}_*\right]$ (F.O 1) $I_{R(max)}$		F.O. x I * i(max)	Measure	
$\mathbf{V}_{\mathrm{T}}$	I <sub>OFF</sub> + (F.O1) I <sub>R(max)</sub> *	Measure	F.O. x I* i(max)		Free inputs open

$$F.I. = fan-in$$

## MEASUREMENT OF DYNAMIC CHARACTERISTICS



Test Circuit for Propagation Delay/Fan-out Measurements



Waveform propagated through two stages. Average propagation delay per stage

$$t_{d(avg)} = \frac{t_{d1} + t_{d2}}{4}$$

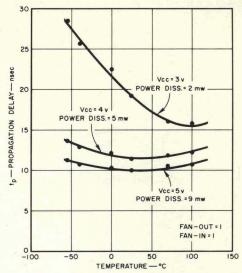
Waveforms and Time Delays

<sup>\*</sup> Definitions and values for temperatures from -55 to +  $70^{\circ}$ C obtained from table on opposite page.

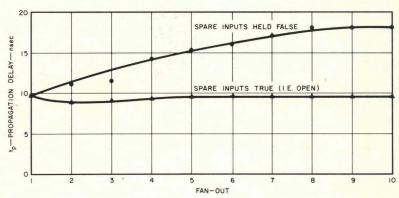
## DYNAMIC CHARACTERISTICS

	FAN-OUT								
TIME	i	(FREE INPUTS)	(FREE INPUTS) HELD FALSE	UNIT					
tr (O-I (TRANSIENT)	10	18	30	nsec					
(TRANSIENT)	5	20	20	nsec					

Typical Rise and Fall Times  $V_{CC} = 4 \text{ volts, } + 25^{\circ}C$ 

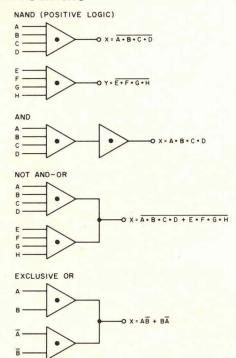


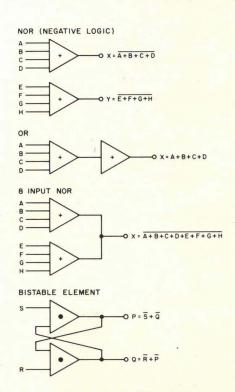
Typical Propagation Delay vs. Voltage and Temp



Effect of Loading on Propagation Delay

## LOGIC DIAGRAMS





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